

AMENDMENT TO THE CLAIMS

Please **Cancel** claims 1-10 as follows.

Please **ADD** claims 11-30 as follows.

The claims in this listing will replace all prior versions, and listings, of claims in the application.

Listing of claims

Claims 1.-10 (cancel)

11. (new) An arrangement for increasing a packing density on a printed circuit with surface mounted electrical components the printed circuit comprising:

two films pressed against one another with a dielectric arranged between them; and
at least one of mutually opposite faces of the films being fitted with surface mounted electrical components via holes being provided in the printed circuit-to connect the two films,
wherein each via hole of the via holes are a direct connection between the mutually opposite faces of the films.

12. (new) The arrangement as claimed in claim 11, further comprising further surface mounted electrical components arranged on faces of the two films which are not mutually opposite.

13. (new) The arrangement as claimed in claim 11, further comprising a further layer of a dielectric and a further film being applied to at least one face of the printed circuit.

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14. (new) The arrangement as claimed in claim 11, wherein the two films contain copper.
15. (new) The arrangement as claimed in claim 11, further comprising first contacts formed on at least one face of the printed circuit.
16. (new) The arrangement as claimed in claim 13, wherein the via holes are formed between the two films and the further film.
17. (new) The arrangement as claimed in claim 11, wherein the surface mounted electrical components are resistors, coils or capacitors.
18. (new) A stack having a plurality of printed circuits as claimed in claim 11 arranged one on top of another.
19. (new) The arrangement as claimed in claim 14, wherein the via holes are formed between the two films and a further film.
20. (new) The arrangement as claimed in claim 15, wherein the via holes are formed between the two films and a further film.
21. (new) The arrangement as claimed in claim 11, wherein the two films are compressed films.
22. (new) A process for fabricating a printed circuit, comprising:

providing two films against one another, the two films having mutually opposite faces;
arranging a dielectric between the two films; and
fitting at least one of the mutually opposite faces of the films with surface mounted electrical components and via holes,
wherein each via hole of the via holes are arranged in direct connection between the mutually opposite faces of the films.

23. (new) The process as claimed in claim 22, further comprising providing a further layer of dielectric and a further film applied to at least one face of the two films.

24. (new) The process as claimed in claim 22, wherein the via holes are microvias.

25. (new) The process as claimed in claim 22, wherein the via holes are produced by one of drilling, electroplating and etching processes.

26. (new) The process as claimed in claim 22, further comprising pressing together the two films.

27. (new) The process as claimed in claim 22, further comprising arranging further surface mounted electrical components on faces of the two films which are not mutually opposite.

28. (new) The process as claimed in claim 22, further comprising embedding the surface mounted electrical components in the dielectric.

29. (new) The process as claimed in claim 22, further comprising soldering the surface mounted electrical components to the two films.

30. (new) The process as claimed in claim 22, further comprising providing first contacts which are formed on at least one face of the two films such that electrical connections are made to another printed circuit.